

IN THE CLAIMS:

Kindly cancel claims 1-18 without prejudice or admission and add the following new claims 19-42 as shown in the following listing of claims, which replaces all previous versions and listings of claims.

19. (new) A method of fabricating a part comprising the steps of:

forming a sacrificial material layer on a base material;

forming a part forming layer on a surface of the sacrificial material layer of a material different from that of the sacrificial material layer;

shaping the part forming layer by a machining process to define an outer configuration of the part; and

separating the shaped part forming layer from the base material to obtain a fabricated part by selectively removing only the sacrificial material layer.

20. (new) A method of fabricating a part according to claim 19; wherein the step of shaping the part forming layer step comprises the step of forming a groove having a predetermined width in the part forming layer along the outer configuration of the part by the machining process.

21. (new) A method of fabricating a part according to claim 20; wherein the machining process used in the step of shaping the part forming layer comprises the steps of arranging a machining electrode having a desired shape in a machining solution opposed to the part forming layer, and moving at least one of the machining electrode and the part forming layer relative to the other along a path corresponding to the outer configuration of the part while applying a voltage between the part forming layer and the machining electrode.

22. (new) A method of fabricating a part comprising the steps of:

forming a part forming layer on a base material of a material different from that of the base material;

shaping the part forming layer by a machining process to define an outer configuration of the part; and

separating the shaped part forming layer from the base material to obtain a fabricated part by selectively removing at least a portion of the base material.

23. (new) A method of fabricating a part according to claim 22; wherein the step of shaping the part forming layer comprises the step of forming a groove having a predetermined width in the part forming layer along the outer configuration of the part by the machining process.

24. (new) A method of fabricating a part according to claim 23; wherein the machining process used in the step of shaping the part forming layer comprises the steps of arranging a machining electrode having a pertinent shape in a machining solution opposed to the part forming layer, and moving at least one of the machining electrode and the part forming layer relative to the other along a path corresponding to the outer configuration of the part while applying a voltage between the part forming layer and the machining electrode.

25. (new) A method of fabricating a part comprising the steps of:

forming a peeling layer on a surface of a base material by subjecting the base material to a surface treatment;

forming a part forming layer on a surface of the peeling layer;

shaping the part forming layer by a machining process to define an outer configuration of the part; and

separating the shaped part forming layer from the base material at the surface of the peeling layer to obtain a fabricated part.

26. (new) A method of fabricating a part according to claim 25; wherein the step of shaping the part forming layer comprises the step of forming a groove having a predetermined width in the part forming layer along the outer configuration of the part by the machining process.

27. (new) A method of fabricating a part according to claim 26; wherein the machining process used in the step of shaping the part forming layer comprises the steps of arranging a machining electrode having a pertinent shape in a machining solution opposed to the part forming layer, and moving at least one of the machining electrode and the part forming layer relative to the other along a path corresponding to the outer configuration of the part while applying a voltage between the part forming layer and the machining electrode.

28. (new) A method of fabricating a part having a fixed portion and a movable portion, comprising the steps of:

forming a sacrificial material layer on a base material;

removing a portion of the sacrificial layer to expose a portion of the base material;

forming a part forming layer on a surface of the sacrificial material layer and the exposed portion of the base

material, the part forming layer being comprised of a material different from that of the sacrificial material layer;

shaping a portion of the part forming layer formed on the sacrificial material layer using a machining process to define an outer configuration of the movable portion of the part; and

separating the part forming layer except for the fixed portion from the base material by selectively removing only the sacrificial layer to thereby form the movable portion of the part, so that the movable portion of the part is movable relative to the base material and the fixed portion of the part is fixed relative to the base material.

29. (new) A method of fabricating a part according to claim 28; wherein the step of shaping a portion of the part forming layer comprises the step of forming a groove having a predetermined width in the part forming layer along the outer configuration of the movable portion of the part by the machining process.

30. (new) A method of fabricating a part according to claim 29; wherein the machining process used in the step of shaping a portion of the part forming layer comprises the steps of arranging a machining electrode having a desired shape in a machining solution opposed to the part forming

layer, and moving at least one of the machining electrode and the part forming layer relative to the other along a path corresponding to the outer configuration of the part while applying a voltage between the part forming layer and the machining electrode.

31. (new) A method of fabricating a part having a fixed portion and a movable portion, comprising the steps of:

forming a sacrificial material layer to cover a surface of a base material except for an exposed portion of the base material surface on which a fixed portion of the part is to be formed;

forming a part forming layer on a surface of the sacrificial material layer and the exposed portion of the base material surface, the part forming layer being comprised of a material different from that of the sacrificial material layer;

shaping a portion of the part forming layer formed on the sacrificial material layer using a machining process to define an outer configuration of the movable portion of the part; and

separating the part forming layer except for the fixed portion from the base material by selectively removing only the sacrificial layer to thereby form the movable portion

of the part, so that the movable portion of the part is movable relative to the base material and the fixed portion of the part is fixed relative to the base material.

32. (new) A method of fabricating a part according to claim 31; wherein the step of shaping a portion of the part forming layer comprises the step of forming a groove having a predetermined width in the part forming layer along the outer configuration of the movable portion of the part by the machining process.

33. (new) A method of fabricating a part according to claim 32; wherein the machining process used in the step of shaping a portion of the part forming layer comprises the steps of arranging a machining electrode having a desired shape in a machining solution opposed to the part forming layer, and moving at least one of the machining electrode and the part forming layer relative to the other along a path corresponding to the outer configuration of the part while applying a voltage between the part forming layer and the machining electrode.

34. (new) A method of fabricating a part having a fixed portion and a movable portion, comprising the steps of:  
forming a peeling layer to cover a surface of a base material except for an exposed portion of the base material surface on which a fixed portion of the part is to be formed;

forming a part forming layer on a surface of the peeling layer and the exposed portion of the base material surface;

shaping a portion of the part forming layer formed on the peeling layer using a machining process to define an outer configuration of the movable portion of the part; and

separating the part forming layer except for the fixed portion from the peeling layer to thereby form the movable portion of the part, so that the movable portion of the part is movable relative to the base material and the fixed portion of the part is fixed relative to the base material.

35. (new) A method of fabricating a part according to claim 34; wherein the step of shaping a portion of the part forming layer comprises the step of forming a groove having a predetermined width in the part forming layer along the outer configuration of the movable portion of the part by the machining process.

36. (new) A method of fabricating a part according to claim 35; wherein the machining process used in the step of shaping a portion of the part forming layer comprises the steps of arranging a machining electrode having a desired shape in a machining solution opposed to the part forming



layer, and moving at least one of the machining electrode and the part forming layer relative to the other along a path corresponding to the outer configuration of the part while applying a voltage between the part forming layer and the machining electrode.

37. (new) A method of fabricating a part according to claim 19; wherein the base material is a conductive material, and the sacrificial material layer is a conductive material that can be selectively etched without etching the based material or the part forming layer.

38. (new) A method of fabricating a part according to claim 19; wherein the base material comprises a chromium substrate, the sacrificial material layer comprises a copper thin film formed by electroplating on the chromium substrate and having a thickness of .5  $\mu\text{m}$  or more, and the part forming layer comprises a nickel thin film formed by electroplating on the copper thin film.

39. (new) A method of fabricating a part according to claim 25; wherein the peeling layer comprises an oxidized surface layer formed by oxidizing a surface of the base material.

40. (new) A method of fabricating a part according to claim 28; wherein the base material is a conductive

material, and the sacrificial material layer is a conductive material that can be selectively etched without etching the based material or the part forming layer.

41. (new) A method of fabricating a part according to claim 28; wherein the base material comprises a chromium substrate, the sacrificial material layer comprises a copper thin film formed by electroplating on the chromium substrate and having a thickness of .5  $\mu\text{m}$  or more, and the part forming layer comprises a nickel thin film formed by electroplating on the copper thin film.

42. (new) A method of fabricating a part according to claim 34; wherein the peeling layer comprises an oxidized surface layer formed by oxidizing a surface of the base material.